2SC4208, 2SC4208A

Silicon NPN epitaxial planer type

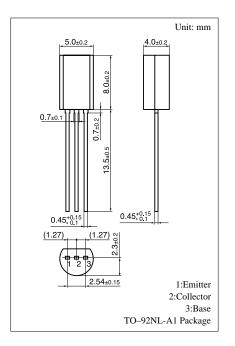
For low-frequency output amplification and driver amplification Complementary to 2SA1619 and 2SA1619A

Features

- Low collector to emitter saturation voltage V_{CE(sat)}.
- Output of 1W is obtained with a complementary pair with 2SA1619 and 2SA1619A.
- Allowing supply with the radial taping.

Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Ratings	Unit	
Collector to	2SC4208	3.7	30	V	
base voltage	2SC4208A	V_{CBO}	60		
Collector to	2SC4208	3.7	25	**	
emitter voltage	2SC4208A	V_{CEO}	50	V	
Emitter to base voltage		V_{EBO}	7	V	
Peak collector current		I_{CP}	1	A	
Collector current		I_{C}	500	mA	
Collector power dissipation		P_{C}	1	W	
Junction temperature		T _j	150	°C	
Storage temperature		$T_{\rm stg}$	-55 ~ +150	°C	



Electrical Characteristics (Ta=25°C)

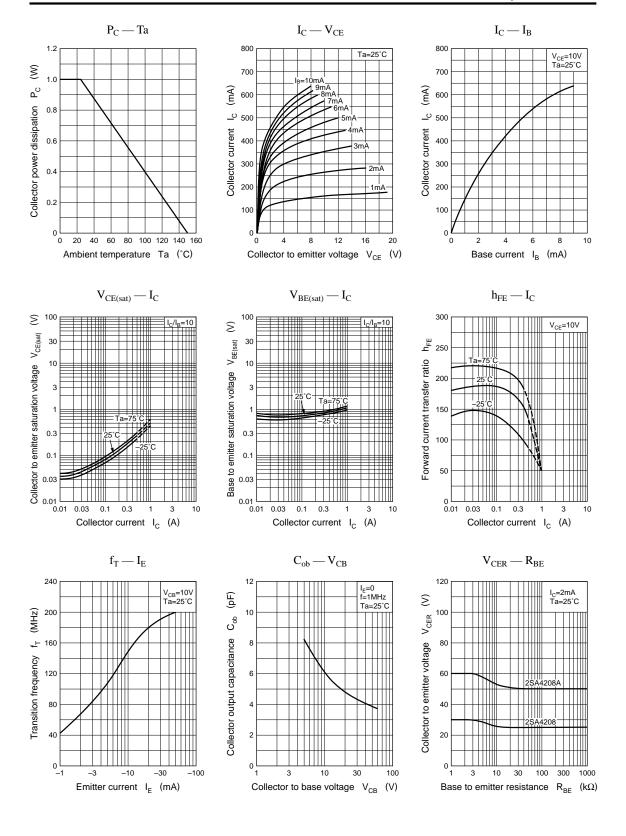
Paramete	Parameter		Conditions	min	typ	max	Unit
Collector cutoff curre	Collector cutoff current		$V_{CB} = 20V, I_E = 0$			0.1	μА
Collector to base	2SC4208	V_{CBO} $I_{C} = 10 \mu A, I_{E} = 0$		30			
voltage	2SC4208A			60			V
Collector to emitter	2SC4208	**	. 10 4 1 0	25			· v
voltage	2SC4208A	V_{CEO}	$I_{C} = 10\text{mA}, I_{B} = 0$	50			
Emitter to base voltage		V _{EBO}	$I_E = 10\mu A, I_C = 0$	7			V
Forward current transfer ratio		h _{FE1} *1	$V_{CE} = 10V, I_C = 150 \text{mA}^{*2}$	85		340	
		h _{FE2}	$V_{CE} = 10V, I_B = 500 \text{mA}^{*2}$	40			
Collector to emitter saturation voltage $V_{CE(sat)}$		V _{CE(sat)}	$I_C = 300 \text{mA}, I_B = 30 \text{mA}$		0.35	0.6	V
Base to emitter saturation voltage $V_{BE(sat)}$			$I_C = 300 \text{mA}, I_B = 30 \text{mA}$		1.1	1.5	V
Transition frequency f		f_T	$V_{CB} = 10V, I_E = -50mA, f = 200MHz$		150		MHz
Collector output capacitance		C _{ob}	$V_{CB} = 10V, I_E = 0, f = 1MHz$		6	15	pF

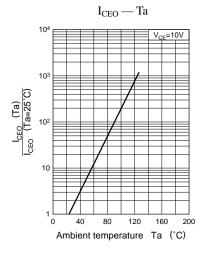
*2 Pulse measurement

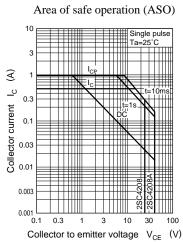
^{*1}hFE1 Rank classification

Rank	Q	R	S	
h _{FE1}	85 ~ 170	120 ~ 240	170 ~ 340	

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